



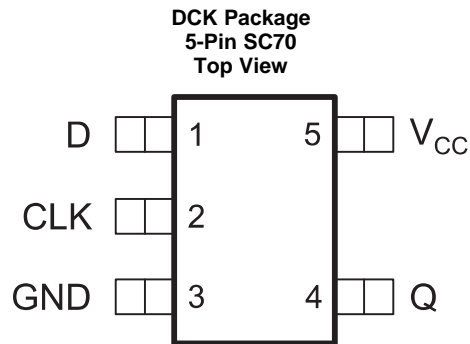
## 目录

<b>1</b>	特性 .....	<b>1</b>	<b>7</b>	<b>Parameter Measurement Information</b> .....	<b>9</b>
<b>2</b>	应用 .....	<b>1</b>	<b>8</b>	<b>Detailed Description</b> .....	<b>11</b>
<b>3</b>	说明 .....	<b>1</b>	8.1	Overview .....	11
<b>4</b>	修订历史记录 .....	<b>2</b>	8.2	Functional Block Diagram .....	11
<b>5</b>	<b>Pin Configuration and Functions</b> .....	<b>3</b>	8.3	Feature Description .....	11
<b>6</b>	<b>Specifications</b> .....	<b>4</b>	8.4	Device Functional Modes .....	12
6.1	Absolute Maximum Ratings .....	4	<b>9</b>	<b>Application and Implementation</b> .....	<b>13</b>
6.2	ESD Ratings .....	4	9.1	Application Information .....	13
6.3	Recommended Operating Conditions .....	5	9.2	Typical Application .....	13
6.4	Thermal Information .....	5	<b>10</b>	<b>Power Supply Recommendations</b> .....	<b>14</b>
6.5	Electrical Characteristics .....	6	<b>11</b>	<b>Layout</b> .....	<b>14</b>
6.6	Timing Requirements: $T_A = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$ .....	6	11.1	Layout Guidelines .....	14
6.7	Timing Requirements: $T_A = -40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$ .....	6	11.2	Layout Example .....	14
6.8	Switching Characteristics: $C_L = 15\text{ pF}$ , $T_A = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$ .....	7	<b>12</b>	<b>器件和文档支持</b> .....	<b>15</b>
6.9	Switching Characteristics: $C_L = 30$ or $50\text{ pF}$ , $T_A = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$ .....	7	12.1	文档支持 .....	15
6.10	Switching Characteristics: $C_L = 30\text{ pF}$ or $50\text{ pF}$ , $T_A = -40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$ .....	7	12.2	接收文档更新通知 .....	15
6.11	Operating Characteristics .....	7	12.3	社区资源 .....	15
6.12	Typical Characteristics .....	8	12.4	商标 .....	15
			12.5	静电放电警告 .....	15
			12.6	Glossary .....	15
			<b>13</b>	<b>机械、封装和可订购信息</b> .....	<b>15</b>

## 4 修订历史记录

日期	修订版本	注释
2017 年 3 月	*	首次发布。

## 5 Pin Configuration and Functions



See mechanical drawings for dimensions.

### Pin Functions

PIN		I/O	DESCRIPTION
NAME	DCK		
D	1	I	Data input
CLK	2	I	Positive-Edge-Triggered Clock input
GND	3	—	Ground
Q	4	O	Non-inverted output
V <sub>CC</sub>	5	—	Positive Supply

## 6 Specifications

### 6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

		MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage	-0.5	6.5	V
V <sub>I</sub>	Input voltage <sup>(2)</sup>	-0.5	6.5	V
V <sub>O</sub>	Voltage range applied to any output in the high-impedance or power-off state <sup>(2)</sup>	-0.5	6.5	V
V <sub>O</sub>	Voltage range applied to any output in the high or low state <sup>(2)(3)</sup>	-0.5	V <sub>CC</sub> + 0.5	V
I <sub>IK</sub>	Input clamp current	V <sub>I</sub> < 0	-50	mA
I <sub>OK</sub>	Output clamp current	V <sub>O</sub> < 0	-50	mA
I <sub>O</sub>	Continuous output current		±50	mA
	Continuous current through V <sub>CC</sub> or GND		±100	mA
T <sub>stg</sub>	Storage temperature	-65	150	°C
T <sub>J</sub>	Junction temperature		150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The value of V<sub>CC</sub> is provided in the *Recommended Operating Conditions* table.

### 6.2 ESD Ratings

		VALUE	UNIT
V <sub>(ESD)</sub>	Electrostatic discharge	Human-body model (HBM), per AEC Q100-002 <sup>(1)</sup>	±4000
		Charged-device model (CDM), per AEC Q100-011	±1000

- (1) AEC Q100-002 indicates that HBM stressing shall be in accordance with the ANSI/ESDA/JEDEC JS-001 specification.

### 6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

		MIN	MAX	UNIT	
V <sub>CC</sub>	Supply voltage	Operating	1.65	5.5	V
		Data retention only	1.5		
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 1.65 V to 1.95 V	0.65 × V <sub>CC</sub>		V
		V <sub>CC</sub> = 2.3 V to 2.7 V	1.7		
		V <sub>CC</sub> = 3 V to 3.6 V	2		
		V <sub>CC</sub> = 4.5 V to 5.5 V	0.7 × V <sub>CC</sub>		
V <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 1.65 V to 1.95 V	0.35 × V <sub>CC</sub>		V
		V <sub>CC</sub> = 2.3 V to 2.7 V	0.7		
		V <sub>CC</sub> = 3 V to 3.6 V	0.8		
		V <sub>CC</sub> = 4.5 V to 5.5 V	0.3 × V <sub>CC</sub>		
V <sub>I</sub>	Input voltage	0	5.5	V	
V <sub>O</sub>	Output voltage	0	V <sub>CC</sub>	V	
I <sub>OH</sub>	High-level output current	V <sub>CC</sub> = 1.65 V	–4		mA
		V <sub>CC</sub> = 2.3 V	–8		
		V <sub>CC</sub> = 3 V	–16		
			–24		
		V <sub>CC</sub> = 4.5 V	–32		
I <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 1.65 V	4		mA
		V <sub>CC</sub> = 2.3 V	8		
		V <sub>CC</sub> = 3 V	16		
			24		
		V <sub>CC</sub> = 4.5 V	32		
Δt/Δv	Input transition rise or fall rate	V <sub>CC</sub> = 1.8 V ± 0.15 V, 2.5 V ± 0.2 V	20		ns/V
		V <sub>CC</sub> = 3.3 V ± 0.3 V	10		
		V <sub>CC</sub> = 5 V ± 0.5 V	5		
T <sub>A</sub>	Operating free-air temperature	–40	125	°C	

(1) All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. See [Implications of Slow or Floating CMOS Inputs](#), SCBA004.

### 6.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>		SN74LVC1G79-Q1		UNIT
		DCK		
		5 PINS		
R <sub>θJA</sub>	Junction-to-ambient thermal resistance	277.6		°C/W
R <sub>θJC(top)</sub>	Junction-to-case (top) thermal resistance	179.5		°C/W
R <sub>θJB</sub>	Junction-to-board thermal resistance	75.9		°C/W
Ψ <sub>JT</sub>	Junction-to-top characterization parameter	49.7		°C/W
Ψ <sub>JB</sub>	Junction-to-board characterization parameter	75.1		°C/W

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

## 6.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	T <sub>A</sub> = -40°C to +85°C			T <sub>A</sub> = -40°C to +125°C			UNIT
			MIN	TYP <sup>(1)</sup>	MAX	MIN	TYP <sup>(1)</sup>	MAX	
V <sub>OH</sub>	I <sub>OH</sub> = -100 μA	1.65 V to 5.5 V	V <sub>CC</sub> - 0.1			V <sub>CC</sub> - 0.1			V
	I <sub>OH</sub> = -4 mA	1.65 V	1.2			1.2			
	I <sub>OH</sub> = -8 mA	2.3 V	1.9			1.9			
	I <sub>OH</sub> = -16 mA	3 V	2.4			2.4			
	I <sub>OH</sub> = -24 mA		2.3			2.3			
	I <sub>OH</sub> = -32 mA	4.5 V	3.8			3.8			
V <sub>OL</sub>	I <sub>OL</sub> = 100 μA	1.65 V to 5.5 V				0.1			V
	I <sub>OL</sub> = 4 mA	1.65 V				0.45			
	I <sub>OL</sub> = 8 mA	2.3 V				0.3			
	I <sub>OL</sub> = 16 mA	3 V				0.4			
	I <sub>OL</sub> = 24 mA					0.55			
	I <sub>OL</sub> = 32 mA	4.5 V				0.55			
I <sub>I</sub>	All inputs	V <sub>I</sub> = 5.5 V or GND	0 to 5.5 V			±10			μA
I <sub>off</sub>		V <sub>I</sub> or V <sub>O</sub> = 5.5 V	0			±10			μA
I <sub>CC</sub>		V <sub>I</sub> = 5.5 V or GND, I <sub>O</sub> = 0	1.65 V to 5.5 V			10			μA
ΔI <sub>CC</sub>		One input at V <sub>CC</sub> - 0.6 V, Other inputs at V <sub>CC</sub> or GND	3 V to 5.5 V			500			μA
C <sub>i</sub>		V <sub>I</sub> = V <sub>CC</sub> or GND	3.3 V			4			pF

 (1) All typical values are at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C.

## 6.6 Timing Requirements: T<sub>A</sub> = -40°C to +85°C

 over operating free-air temperature range (unless otherwise noted) (see [Figure 3](#))

PARAMETER		T <sub>A</sub> = -40°C to +85°C								UNIT	
		V <sub>CC</sub> = 1.8 ± 0.15 V		V <sub>CC</sub> = 2.5 ± 0.2 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		V <sub>CC</sub> = 5 V ± 0.5 V			
		MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX		
f <sub>clock</sub>	Clock frequency	160		160		160		160		MHz	
t <sub>w</sub>	Pulse duration, CLK high or low	2.5		2.5		2.5		2.5		ns	
t <sub>su</sub>	Setup time before CLK↑	Data high	2.2		1.4		1.3		1.2		ns
		Data low	2.6		1.4		1.3		1.2		
t <sub>h</sub>	Hold time, data after CLK↑	0.3		0.4		1		0.5		ns	

## 6.7 Timing Requirements: T<sub>A</sub> = -40°C to +125°C

 over operating free-air temperature range (unless otherwise noted) (see [Figure 3](#))

PARAMETER		T <sub>A</sub> = -40°C to +125°C								UNIT	
		V <sub>CC</sub> = 1.8 ± 0.15 V		V <sub>CC</sub> = 2.5 ± 0.2 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		V <sub>CC</sub> = 5 V ± 0.5 V			
		MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX		
f <sub>clock</sub>	Clock frequency	160		160		160		160		MHz	
t <sub>w</sub>	Pulse duration, CLK high or low	2.5		2.5		2.5		2.5		ns	
t <sub>su</sub>	Setup time before CLK↑	Data high	2.2		1.4		1.3		1.2		ns
		Data low	2.6		1.4		1.3		1.2		
t <sub>h</sub>	Hold time, data after CLK↑	0.3		0.4		1		0.5		ns	

### 6.8 Switching Characteristics: $C_L = 15\text{ pF}$ , $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$

over recommended operating free-air temperature range,  $C_L = 15\text{ pF}$  (unless otherwise noted) (see [Figure 3](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$								UNIT
			$V_{CC} = 1.8\text{ V}$ $\pm 0.15\text{ V}$		$V_{CC} = 2.5\text{ V}$ $\pm 0.2\text{ V}$		$V_{CC} = 3.3\text{ V}$ $\pm 0.3\text{ V}$		$V_{CC} = 5\text{ V}$ $\pm 0.5\text{ V}$		
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
$f_{max}$			160		160		160		160		MHz
$t_{pd}$	CLK	Q	2.5	9.1	1.2	6	1	4	0.8	3.8	ns

### 6.9 Switching Characteristics: $C_L = 30$ or $50\text{ pF}$ , $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$

over recommended operating free-air temperature range,  $C_L = 30\text{ pF}$  or  $50\text{ pF}$  (unless otherwise noted) (see [Figure 4](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$								UNIT
			$V_{CC} = 1.8\text{ V}$ $\pm 0.15\text{ V}$		$V_{CC} = 2.5\text{ V}$ $\pm 0.2\text{ V}$		$V_{CC} = 3.3\text{ V}$ $\pm 0.3\text{ V}$		$V_{CC} = 5\text{ V}$ $\pm 0.5\text{ V}$		
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
$f_{max}$			160		160		160		160		MHz
$t_{pd}$	CLK	Q	3.9	9.9	2	7	1.7	5	1	4.5	ns

### 6.10 Switching Characteristics: $C_L = 30\text{ pF}$ or $50\text{ pF}$ , $T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$

over recommended operating free-air temperature range,  $C_L = 30\text{ pF}$  or  $50\text{ pF}$  (unless otherwise noted) (see [Figure 4](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$								UNIT
			$V_{CC} = 1.8\text{ V}$ $\pm 0.15\text{ V}$		$V_{CC} = 2.5\text{ V}$ $\pm 0.2\text{ V}$		$V_{CC} = 3.3\text{ V}$ $\pm 0.3\text{ V}$		$V_{CC} = 5\text{ V}$ $\pm 0.5\text{ V}$		
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
$f_{max}$			160		160		160		160		MHz
$t_{pd}$	CLK	Q	3.9	12	2	8.5	1.7	6	1	5	ns

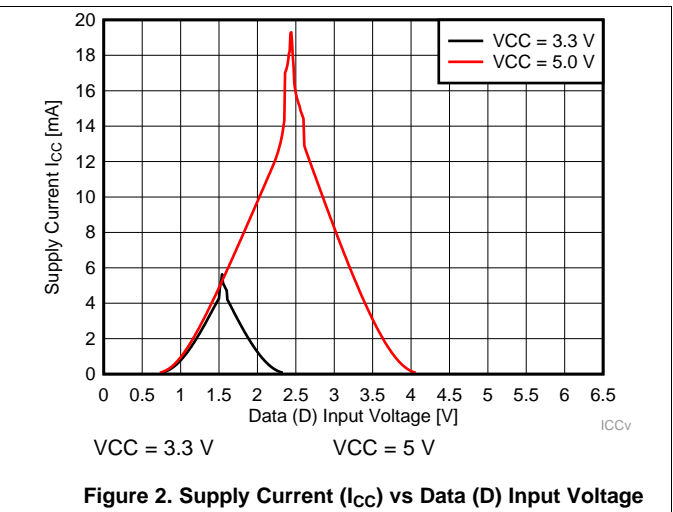
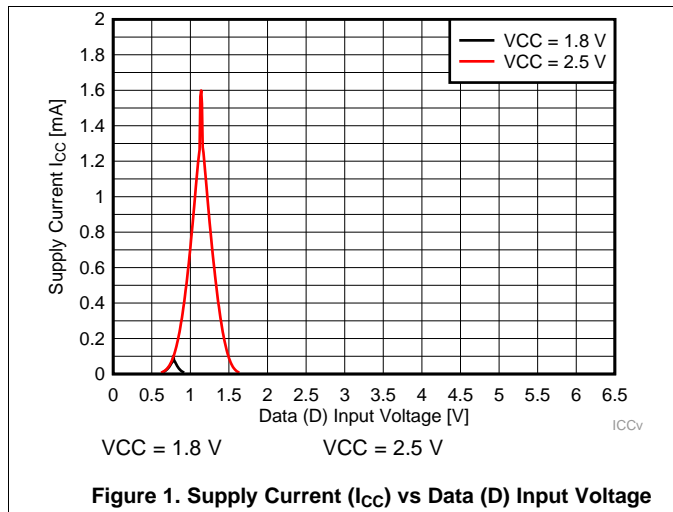
### 6.11 Operating Characteristics

 $T_A = 25^\circ\text{C}$ 

PARAMETER	TEST CONDITIONS	$V_{CC} = 1.8\text{ V}$	$V_{CC} = 2.5\text{ V}$	$V_{CC} = 3.3\text{ V}$	$V_{CC} = 5\text{ V}$	UNIT	
		TYP	TYP	TYP	TYP		
$C_{pd}$	Power dissipation capacitance	f = 10 MHz	26	26	27	30	pF

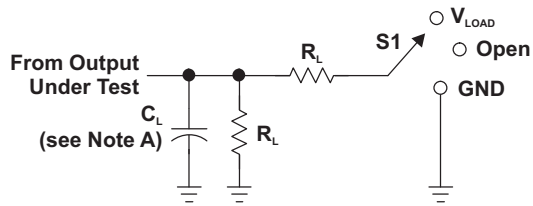
### 6.12 Typical Characteristics

This plot shows the different  $I_{CC}$  values for various voltages on the data input (D). Voltage sweep on the input is from 0 V to 6.5 V.





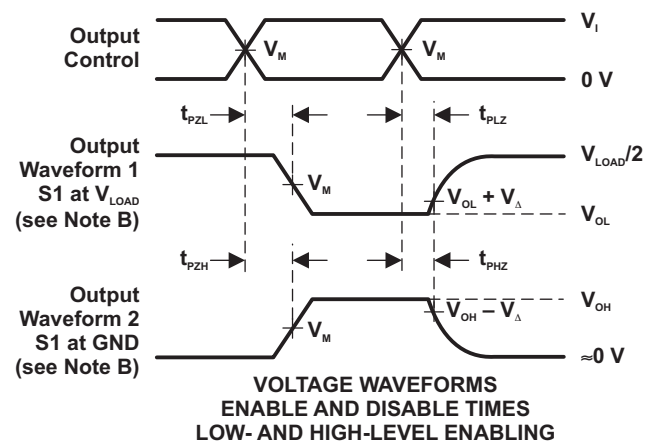
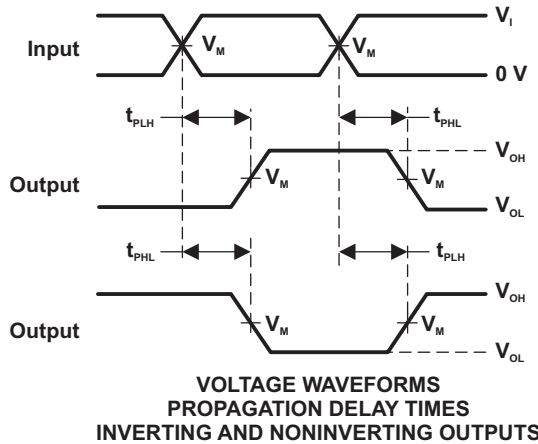
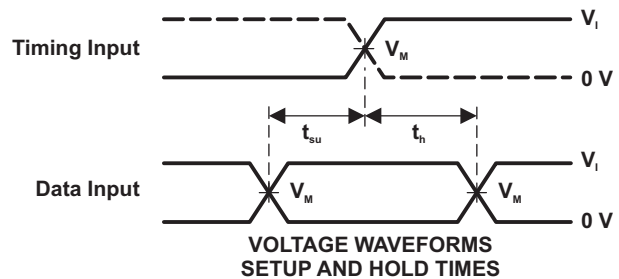
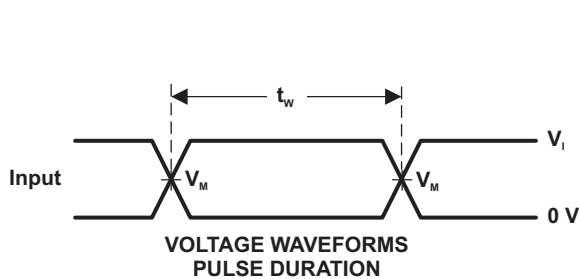
## 7 Parameter Measurement Information



LOAD CIRCUIT

TEST	S1
$t_{PLH}/t_{PHL}$	Open
$t_{PLZ}/t_{PZL}$	$V_{LOAD}$
$t_{PHZ}/t_{PZH}$	GND

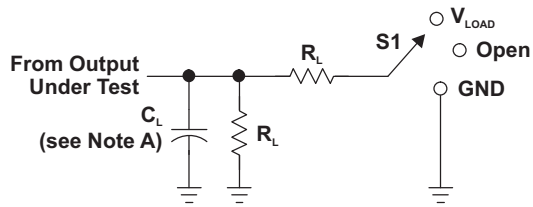
$V_{CC}$	INPUTS		$V_M$	$V_{LOAD}$	$C_L$	$R_L$	$V_{\Delta}$
	$V_i$	$t_r/t_f$					
$1.8 V \pm 0.15 V$	$V_{CC}$	$\leq 2 \text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	15 pF	1 M $\Omega$	0.15 V
$2.5 V \pm 0.2 V$	$V_{CC}$	$\leq 2 \text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	15 pF	1 M $\Omega$	0.15 V
$3.3 V \pm 0.3 V$	3 V	$\leq 2.5 \text{ ns}$	1.5 V	6 V	15 pF	1 M $\Omega$	0.3 V
$5 V \pm 0.5 V$	$V_{CC}$	$\leq 2.5 \text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	15 pF	1 M $\Omega$	0.3 V



- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.  
 C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq 10 \text{ MHz}$ ,  $Z_o = 50 \Omega$ .  
 D. The outputs are measured one at a time, with one transition per measurement.  
 E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .  
 F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .  
 G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .  
 H. All parameters and waveforms are not applicable to all devices.

Figure 3. Load Circuit and Voltage Waveforms

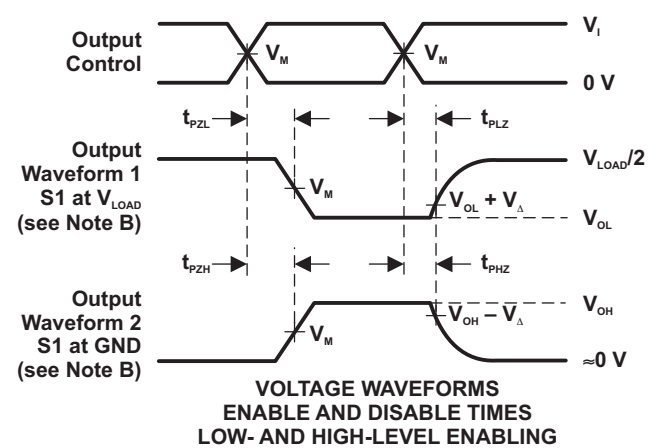
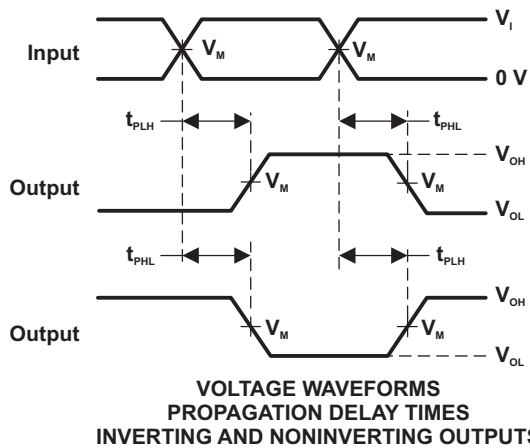
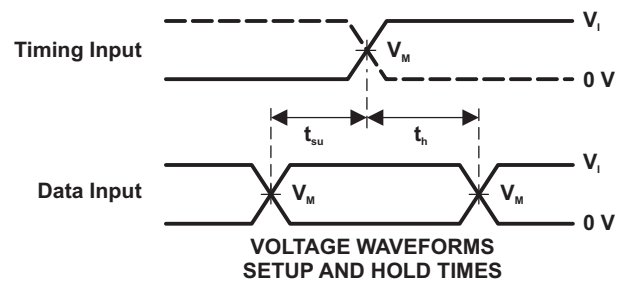
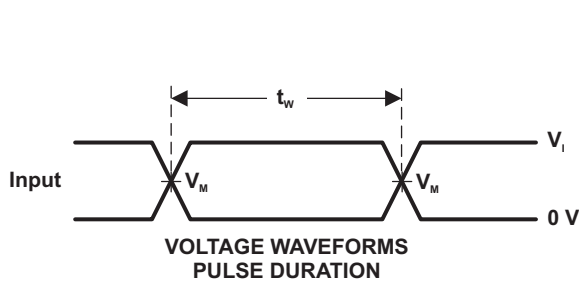
Parameter Measurement Information (continued)



LOAD CIRCUIT

TEST	S1
$t_{PLH}/t_{PHL}$	Open
$t_{PLZ}/t_{PZL}$	$V_{LOAD}$
$t_{PHZ}/t_{PZH}$	GND

$V_{CC}$	INPUTS		$V_M$	$V_{LOAD}$	$C_L$	$R_L$	$V_{\Delta}$
	$V_I$	$t_r/t_f$					
$1.8\text{ V} \pm 0.15\text{ V}$	$V_{CC}$	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	1 k $\Omega$	0.15 V
$2.5\text{ V} \pm 0.2\text{ V}$	$V_{CC}$	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	500 $\Omega$	0.15 V
$3.3\text{ V} \pm 0.3\text{ V}$	3 V	$\leq 2.5\text{ ns}$	1.5 V	6 V	50 pF	500 $\Omega$	0.3 V
$5\text{ V} \pm 0.5\text{ V}$	$V_{CC}$	$\leq 2.5\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	50 pF	500 $\Omega$	0.3 V



- NOTES:
- A.  $C_L$  includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_o = 50\ \Omega$ .
  - D. The outputs are measured one at a time, with one transition per measurement.
  - E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
  - F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{on}$ .
  - G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
  - H. All parameters and waveforms are not applicable to all devices.

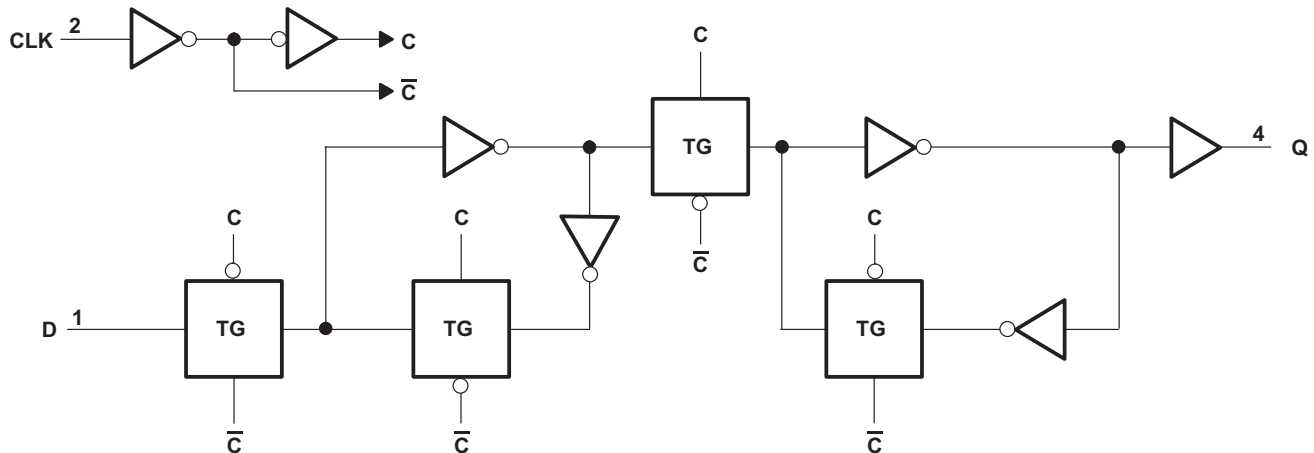
Figure 4. Load Circuit and Voltage Waveforms

## 8 Detailed Description

### 8.1 Overview

The SN74LVC1G79-Q1 is a single positive-edge-triggered D-type flip-flop and is AEC-Q100 qualified for automotive applications. Data at the input (D) is transferred to the output (Q) on the positive-going edge of the clock pulse when the setup time requirement is met. Because the clock triggering occurs at a voltage level, it is not directly related to the rise time of the clock pulse. This allows for data at the input to be changed without affecting the level at the output, following the hold-time interval.

### 8.2 Functional Block Diagram



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Figure 5. Logic Diagram (Positive Logic)

### 8.3 Feature Description

#### 8.3.1 Balanced High-Drive CMOS Push-Pull Outputs

A balanced output allows the device to sink and source similar currents. The high drive capability of this device creates fast edges into light loads so routing and load conditions should be considered to prevent ringing. Additionally, the outputs of this device are capable of driving larger currents than the device can sustain without being damaged. It is important for the power output of the device to be limited to avoid thermal runaway and damage due to over-current. The electrical and thermal limits defined in the [Absolute Maximum Ratings](#) must be followed at all times.

#### 8.3.2 Standard CMOS Inputs

Standard CMOS inputs are high impedance and are typically modeled as a resistor in parallel with the input capacitance given in the [Electrical Characteristics](#). The worst case resistance is calculated with the maximum input voltage, given in the [Recommended Operating Conditions](#), and the maximum input leakage current, given in the [Electrical Characteristics](#), using ohm's law ( $R = V \div I$ ).

Signals applied to the inputs need to have fast edge rates, as defined by  $\Delta t/\Delta v$  in [Recommended Operating Conditions](#) to avoid excessive currents and oscillations. If tolerance to a slow or noisy input signal is required, a device with a Schmitt-trigger input should be utilized to condition the input signal prior to the standard CMOS input.

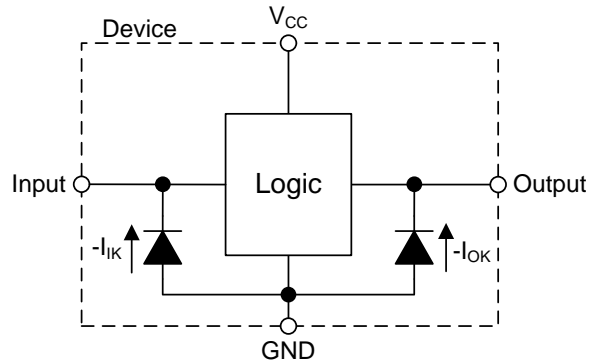
## Feature Description (continued)

### 8.3.3 Clamp Diodes

The inputs and outputs to this device have negative clamping diodes.

**CAUTION**

Voltages beyond the values specified in the [Absolute Maximum Ratings](#) table can cause damage to the device. The input negative-voltage and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.



**Figure 6. Electrical Placement of Clamping Diodes for Each Input and Output**

### 8.3.4 Partial Power Down ( $I_{off}$ )

The inputs and outputs for this device enter a high impedance state when the supply voltage is 0 V. The maximum leakage into or out of any input or output pin on the device is specified by  $I_{off}$  in the [Electrical Characteristics](#).

### 8.3.5 Over-Voltage Tolerant Inputs

Input signals to this device can be driven above the supply voltage so long as they remain below the maximum input voltage value specified in the [Absolute Maximum Ratings](#).

## 8.4 Device Functional Modes

Table 1 lists the functional modes of SN74LVC1G79-Q1.

**Table 1. Function Table**

INPUTS		OUTPUT Y
CLK	D	
↑	H	H
↑	L	L
L	X	$Q_0$

## 9 Application and Implementation

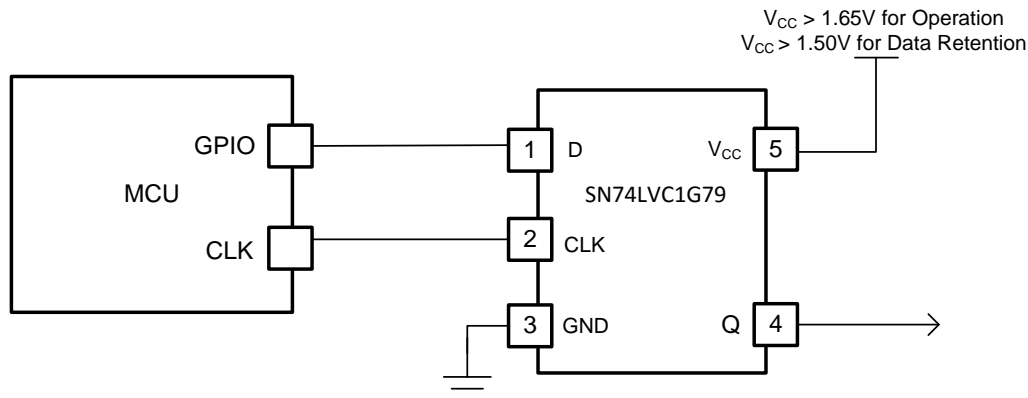
### NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

### 9.1 Application Information

A useful application for the SN74LVC1G79-Q1 is using it as a data latch with low-voltage data retention. This application implements the use of a microcontroller GPIO pin to act as a clock to set the output state and a second GPIO to provide the input data. If the SN74LVC1G79-Q1 is being powered from 1.8 V and there is concern that a power glitch could exist as low as 1.5 V, the device will retain the state of the Q output. An example of this data retention is shown in Figure 8 where the  $V_{CC}$  drops to 1.5 V and the Q output maintains the HIGH output state when  $V_{CC}$  returns to 1.8 V. If the  $V_{CC}$  voltage drops below 1.5 V, data retention is not guaranteed.

### 9.2 Typical Application



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Figure 7. Low Voltage Data Retention With SN74LVC1G79-Q1

#### 9.2.1 Design Requirements

The SN74LVC1G79-Q1 device uses CMOS technology and has balanced output drive. Take care to avoid bus contention because it can drive currents that would exceed maximum limits.

#### 9.2.2 Detailed Design Procedure

- Recommended input conditions:
  - For rise time and fall time specifications, see  $\Delta t/\Delta v$  in [Recommended Operating Conditions](#).
  - For specified high and low levels, see  $V_{IH}$  and  $V_{IL}$  in [Recommended Operating Conditions](#).
  - Input voltages are recommended to not go below 0 V and not exceed 5.5 V for any  $V_{CC}$ . See [Recommended Operating Conditions](#).
- Recommended output conditions:
  - Load currents should not exceed  $\pm 50$  mA. See [Absolute Maximum Ratings](#).
  - Output voltages are recommended to not go below 0 V and not exceed the  $V_{CC}$  voltage. See [Recommended Operating Conditions](#).

## Typical Application (continued)

### 9.2.3 Application Curve

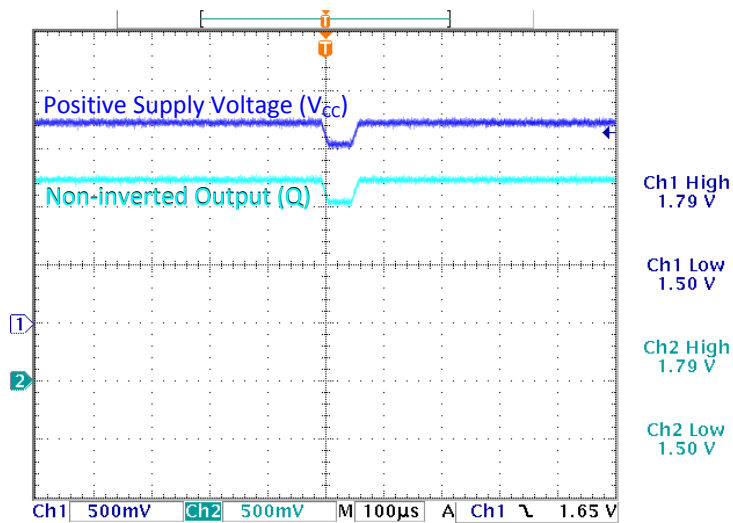


Figure 8. Data Retention With  $V_{CC}$  Glitch Down to 1.5 V

## 10 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating listed in [Recommended Operating Conditions](#). A 0.1- $\mu\text{F}$  bypass capacitor is recommended to be connected from the VCC terminal to GND to prevent power disturbance. To reject different frequencies of noise, use multiple bypass capacitors in parallel. Capacitors with values of 0.1  $\mu\text{F}$  and 1  $\mu\text{F}$  are commonly used in parallel. The bypass capacitor must be installed as close to the power terminal as possible for best results.

## 11 Layout

### 11.1 Layout Guidelines

When a PCB trace turns a corner at a 90° angle, a reflection can occur. A reflection occurs primarily because of the change of width of the trace. At the apex of the turn, the trace width increases to 1.414 times the width. This increase upsets the transmission-line characteristics, especially the distributed capacitance and self-inductance of the trace which results in the reflection. Not all PCB traces can be straight and therefore some traces must turn corners. [Figure 9](#) shows progressively better techniques of rounding corners. Only the last example (BEST) maintains constant trace width and minimizes reflections.

### 11.2 Layout Example

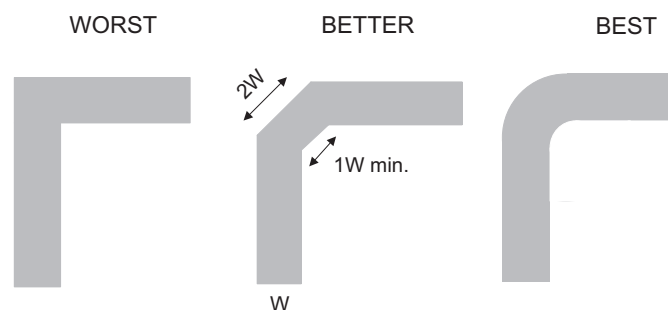


Figure 9. Trace Example

## 12 器件和文档支持

### 12.1 文档支持

#### 12.1.1 相关文档

相关文档请参阅以下部分：

- 《慢速或浮点 CMOS 输入的影响》，SCBA004
- 《了解和解读标准逻辑器件数据表》，SZZA036
- 《计时器件的加电行为》，SCHA005

### 12.2 接收文档更新通知

如需接收文档更新通知，请访问 [www.ti.com.cn](http://www.ti.com.cn) 网站上的器件产品文件夹。点击右上角的提醒我 (Alert me) 注册后，即可每周定期收到已更改的产品信息。有关更改的详细信息，请查阅已修订文档中包含的修订历史记录。

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**Design Support** *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

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### 12.5 静电放电警告



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### 12.6 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

## 13 机械、封装和可订购信息

以下页中包括机械封装、封装和可订购信息。这些信息是针对指定器件可提供的最新数据。这些数据会在无通知且不对本文档进行修订的情况下发生改变。要获得这份数据表的浏览器版本，请查阅左侧导航栏。

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LVC1G79QDCKRQ1	ACTIVE	SC70	DCK	5	3000	RoHS & Green	SN	Level-2-260C-1 YEAR	-40 to 125	16S	<b>Samples</b>
SN74LVC1G79QDCKTQ1	ACTIVE	SC70	DCK	5	250	RoHS & Green	SN	Level-2-260C-1 YEAR	-40 to 125	16S	<b>Samples</b>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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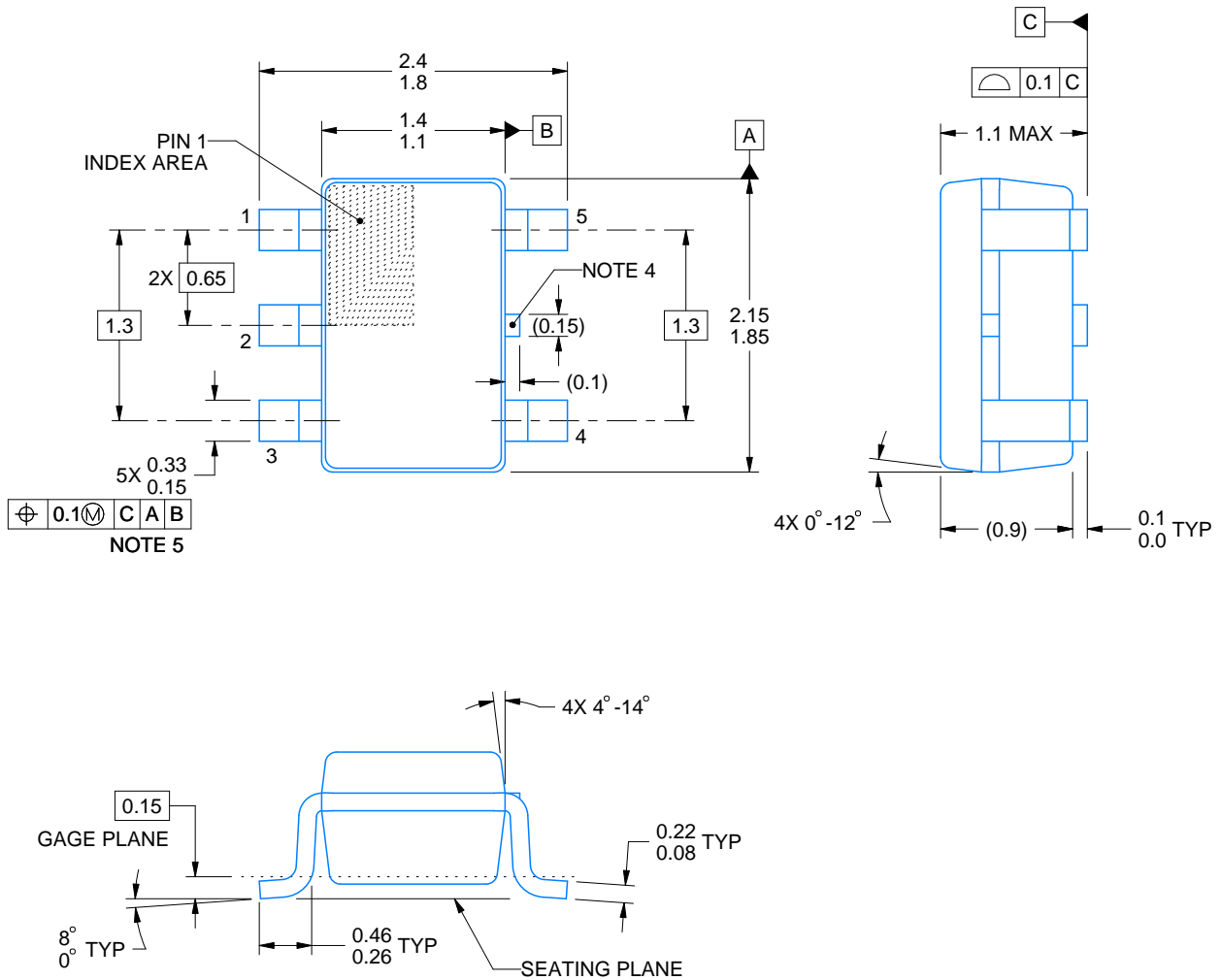
# DCK0005A



# PACKAGE OUTLINE

SOT - 1.1 max height

SMALL OUTLINE TRANSISTOR



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**NOTES:**

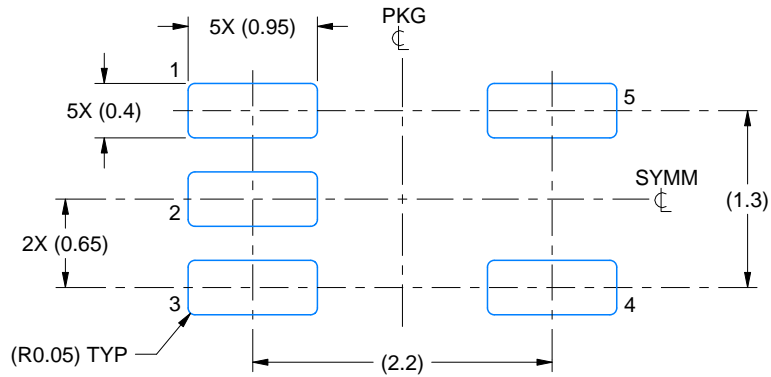
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC MO-203.
4. Support pin may differ or may not be present.
5. Lead width does not comply with JEDEC.
6. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25mm per side

# EXAMPLE BOARD LAYOUT

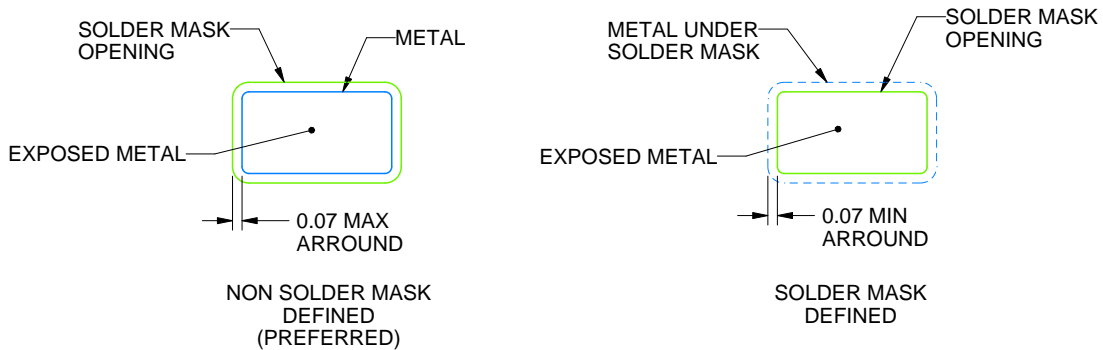
DCK0005A

SOT - 1.1 max height

SMALL OUTLINE TRANSISTOR



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:18X



SOLDER MASK DETAILS

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NOTES: (continued)

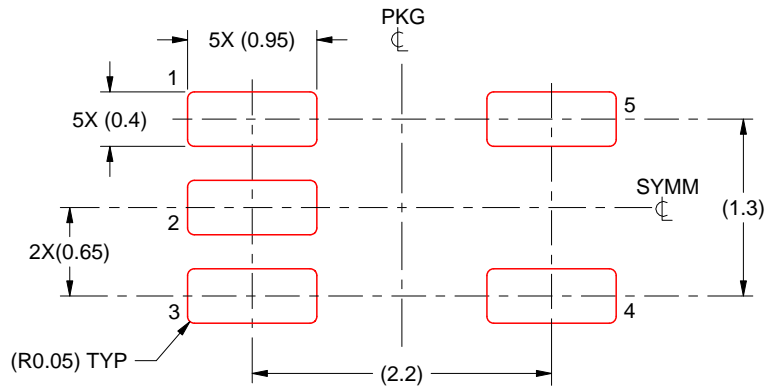
7. Publication IPC-7351 may have alternate designs.
8. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DCK0005A

SOT - 1.1 max height

SMALL OUTLINE TRANSISTOR



SOLDER PASTE EXAMPLE  
BASED ON 0.125 THICK STENCIL  
SCALE: 18X

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NOTES: (continued)

9. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
10. Board assembly site may have different recommendations for stencil design.

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